

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Daewoong Suh	Examiner:	John B. Vigushin
Serial No.:	10/808,192	Group Art Unit:	2841
Filed:	March 24, 2004	Docket:	884.C25US1
Title:	SOLDERING AN ELECTRONICS PACKAGE TO A MOTHERBOARD		
Customer Number:	21186		

INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant requests that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicant with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications are no longer required to be provided to the Office. Notification of this change was provided in the United States Patent and Trademark Office OG Notices dated October 12, 2004. Thus, Applicant has not included copies of any US Patents or Published Applications cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

Respectfully submitted,

DAEWOONG SUH

By his Representatives,

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By / Andrew Peret /
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Under the Freedom of Information Act of 2005, no person is entitled to consent to a reduction of information, unless it contains a valid, specific, written, informed consent.

<p>Substitute for Form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT <small>(Use as many sheets as necessary)</small></p>		<p>Under the Paperwork Reduction Act of 1995, no person is required to respond to a collection of information unless it contains a valid OMB control number.</p> <p>Complete if Known</p> <table border="1"> <tr> <td>Application Number</td> <td>10/808,192</td> </tr> <tr> <td>Filing Date</td> <td>March 24, 2004</td> </tr> <tr> <td>First Named Inventor</td> <td>Suh, Daewoong</td> </tr> <tr> <td>Group Art Unit</td> <td>2841</td> </tr> <tr> <td>Examiner Name</td> <td>Vigushin, John</td> </tr> </table>	Application Number	10/808,192	Filing Date	March 24, 2004	First Named Inventor	Suh, Daewoong	Group Art Unit	2841	Examiner Name	Vigushin, John
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Examiner Name	Vigushin, John											
		<p>Sheet 1 of 1</p>										
<p>Attorney Docket No: 884.C25US1</p>												

US PATENT DOCUMENTS

USPTO PATENT DOCUMENTS

Examiner Initials *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Filing Date if Appropriate
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FOREIGN PATENT DOCUMENTS

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OTHER DOCUMENTS – NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		ROMAN, JOHN W., et al., "Low Stress Die Attach by Low Temperature Transient Liquid Phase Bonding", <u>The International Society for Hybrid Microelectronics (ISHM) Symposium Proceedings</u> , October 1992, (October 1992) 1-6	

EXAMINER

DATE CONSIDERED

Software for Geospatial Data and Image Processing

EXAMINER: Print or reference connected, whether or not citation is in parentheses, and cite the reference in the order it appears in the original document. Close out through citation if not in main body and not connected. Include copy of this form with next communication if applicable. Application to Appendix 1 unique citation distinguishes numbered entries. A Appendix 2 is given to attach a check mark if English language. Translation is attached.